

SCHOTTKY BARRIER DIODE

Features

- 1) Small surface mounting type.
- 2) Ultra low V_F ($V_F=0.5V$ Typ. at 0.2A)
- 3) High reliability.
- 4) We declare that the material of product compliance with RoHS requirements.



DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
FDR40U	6S	3000/Tape&Reel

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V_R	40	Vdc
Peak Forward Current	I_F	350	mAdc
Peak Forward Surge Current	$I_{FM(surge)}$	1500	mAdc

THERMAL CHARACTERISTICS ($T_J=125^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, * $T_A = 25^\circ\text{C}$	P_D	200	mW
Derate above 25°C		1.57	mW/°C
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	635	°C/W
Junction Temperature	T_J	125Max	°C
Storage Temperature Range	T_{stg}	-65 to +125	°C

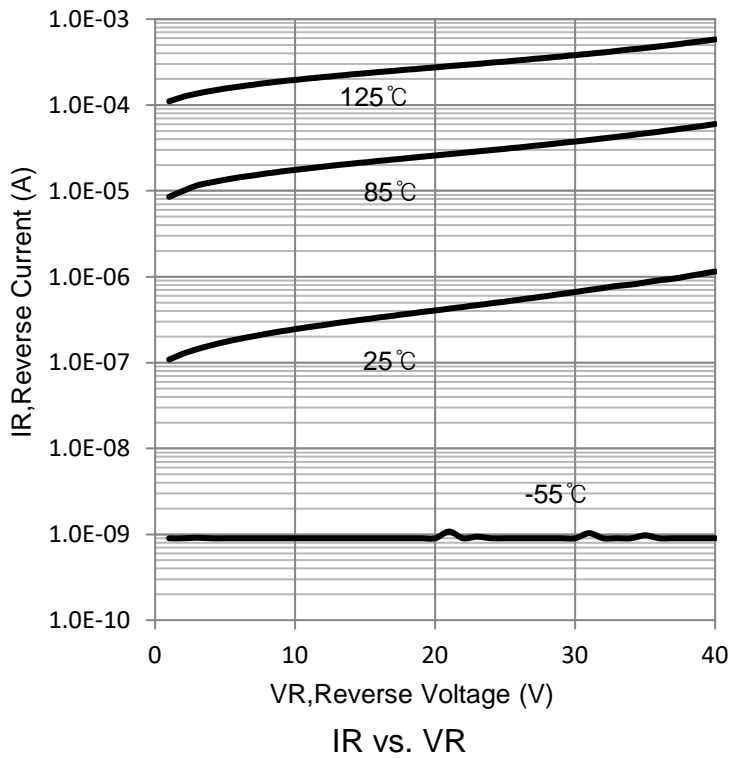
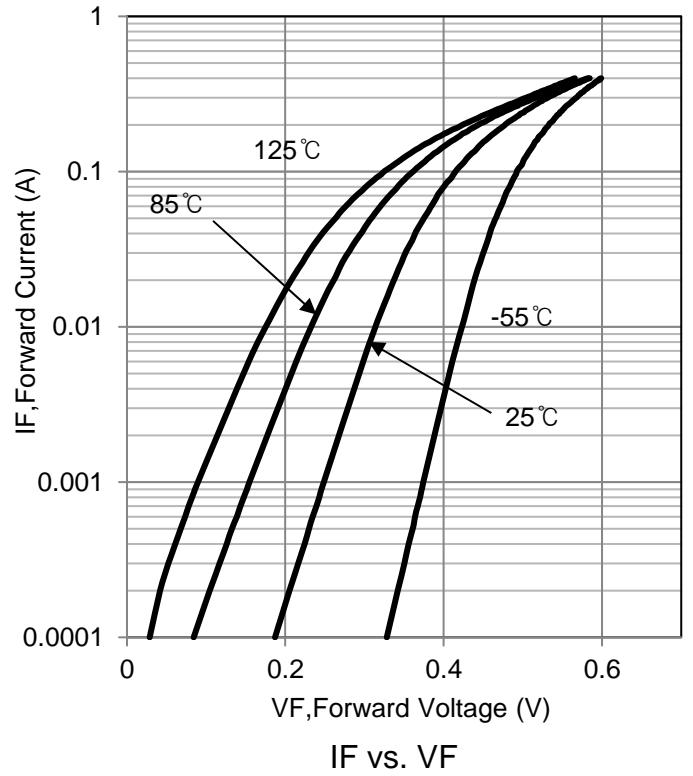
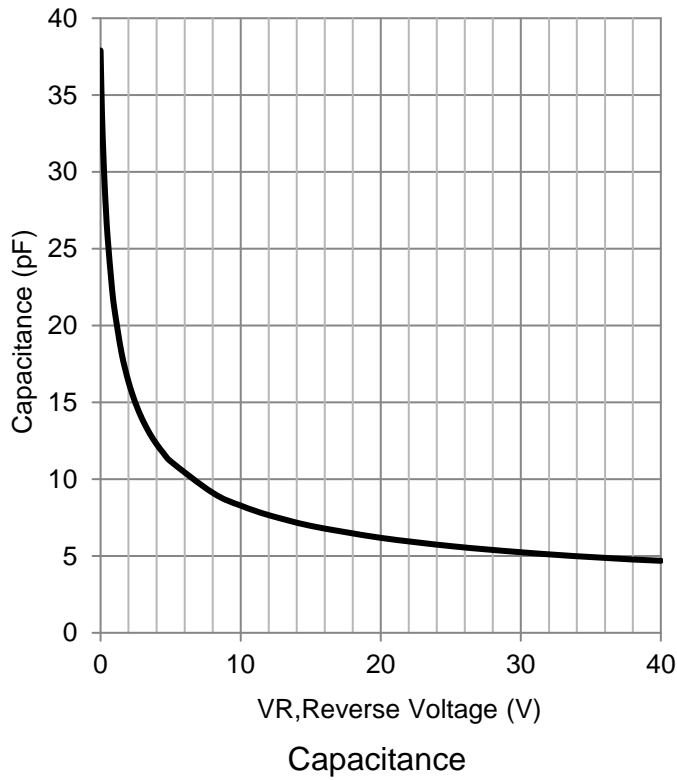
ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Reverse Voltage Leakage Current ($V_R = 25$ Vdc)	I_R	–	1.0	μAdc
Reverse Breakdown Voltage ($I_{BR} = 10$ μAdc)	$V_{(BR)}$	40	–	Vdc
Forward Voltage ($I_F = 20$ mAdc) ($I_F = 200$ mAdc)	V_F	–	370 600	mV

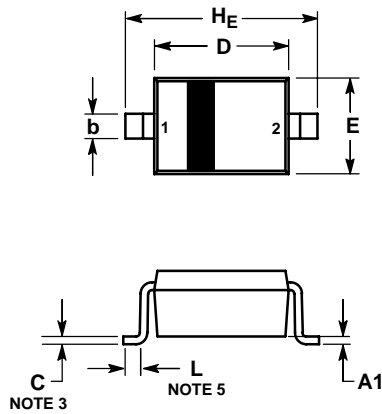
*. FR-5 = 1.0 x 0.75 x 0.062 in.



FDR40U



SOD-323



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
5. DIMENSION L IS MEASURED FROM END OF RADIUS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.30	2.50	2.70	0.090	0.098	0.105

SOLDERING FOOTPRINT*

